

Abstract

**ADHESIVE SHEET AND PROCESS FOR MANUFACTURING  
ELECTRONIC PART**

An adhesive sheet comprising a sheetlike base material and, superimposed on one major surface thereof, an adhesive layer, wherein the average surface roughness on one major surface of the base material is in the range of 0.1 to 3.5 $\mu\text{m}$  and on the other major surface thereof is in the range of 0.05 to 0.7 $\mu\text{m}$ . In this structure, the average surface roughness values on both the major surfaces of the base material as a constituent of the adhesive sheet are regulated so as to fall within respective specified ranges, so that not only can any blocking occurring in backwinding of reeled adhesive sheet be inhibited but also any occurrence of minute unevenness (waving) on the wafer surface after grinding can be inhibited; and further that the transparency of the adhesive sheet can be maintained.

- Fig. 1 -